

[OPTIMIZED CONDUCTIVE LID MOUNTING FOR INTEGRATED CIRCUIT CHIP CARRIERS]

Abstract

An optimized lid mounting for electronic device carriers, using standard manufacturing process steps of semiconductor packaging, optimizing heat dissipation and electromagnetic interference shielding is disclosed. According to the invention, conductive blocks or springs are soldered to ground pads of the chip carrier on their lower side. On the other side, these conductive blocks or springs are electrically connected to the lid with conductive adhesive material such as silicone based material. Furthermore, the lid is thermally connected to the semiconductor chip with electrical insulative adhesive material.